



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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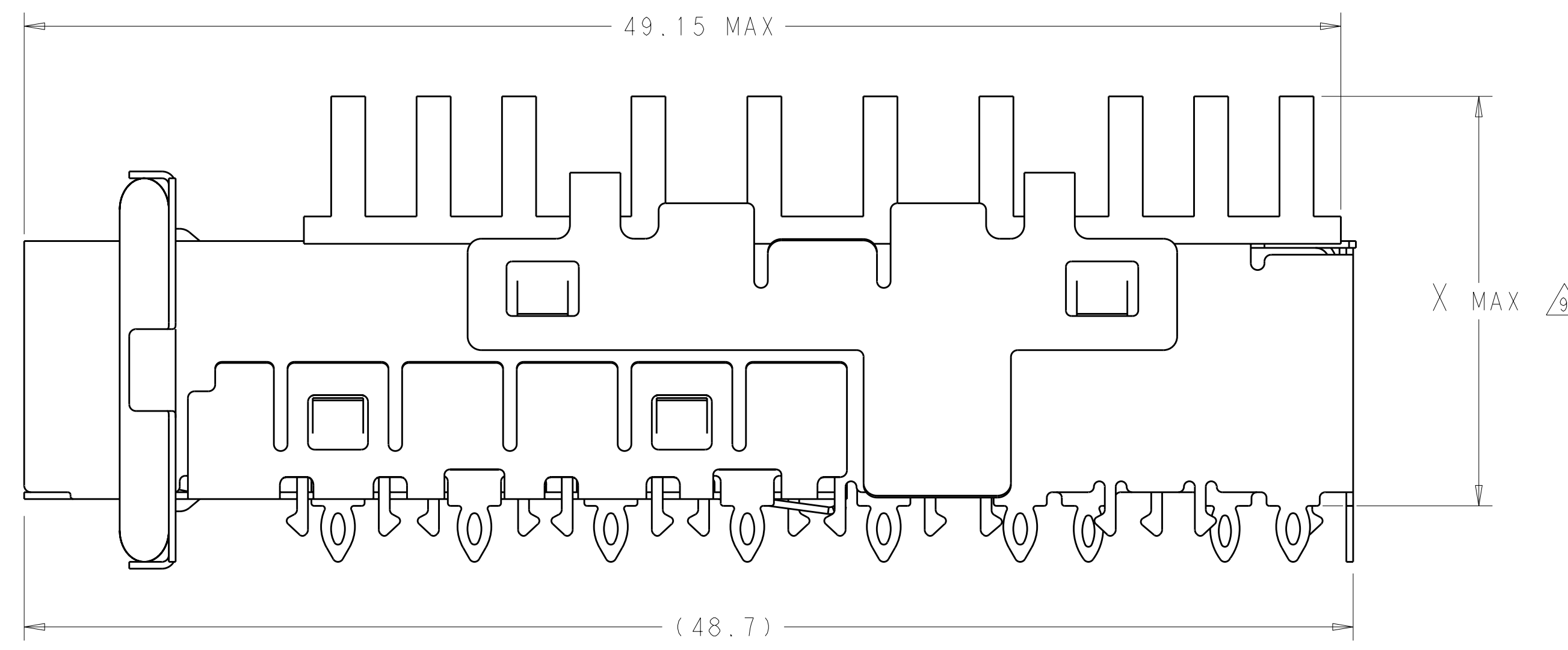
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

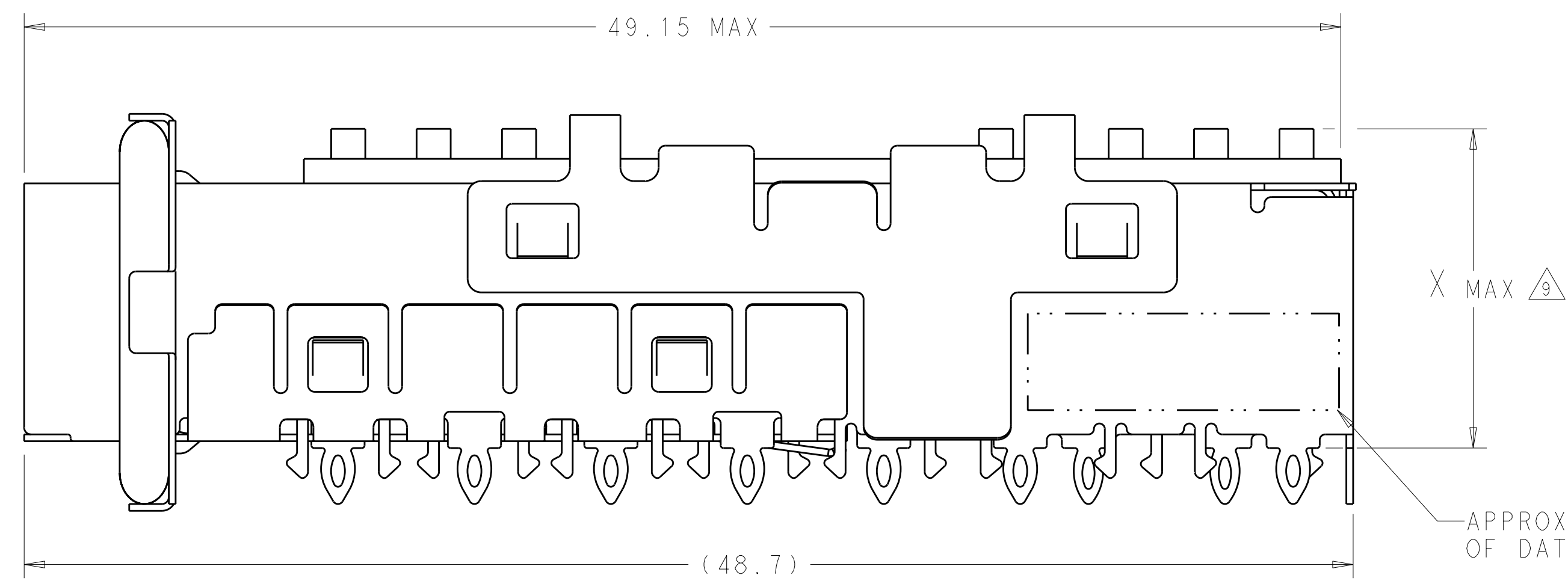
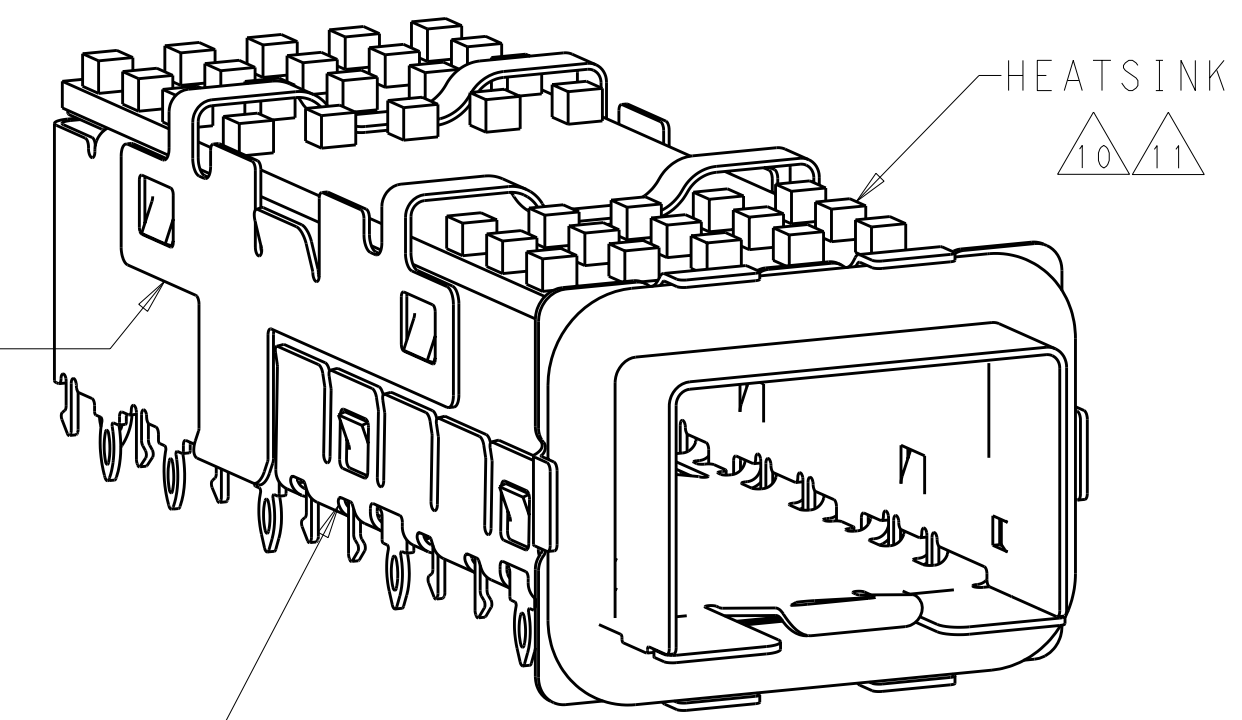


LOC	DIST	REV	DATE	BY	APPD
GP	00	A	10FEB2011	CJV	JTL

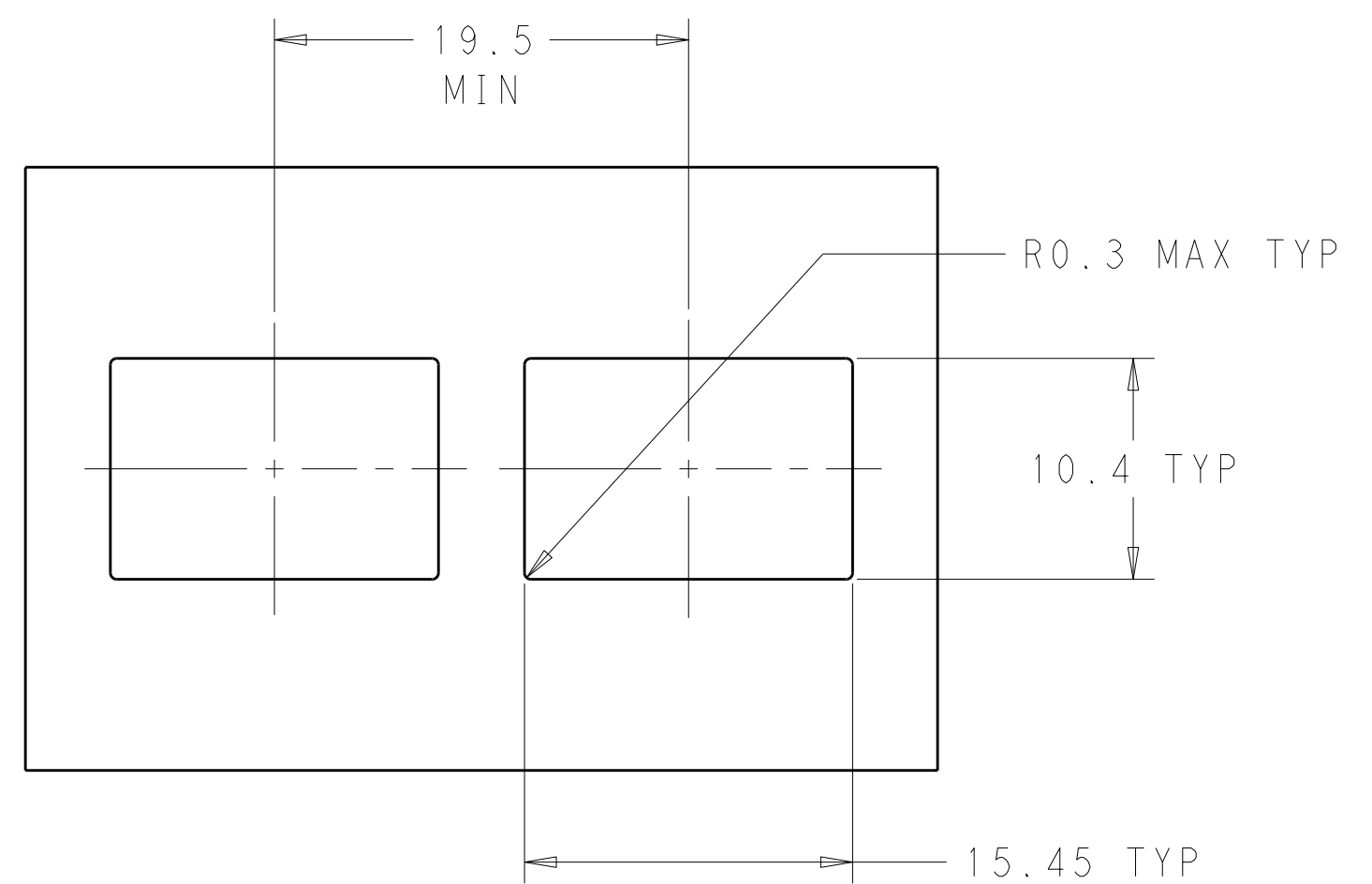
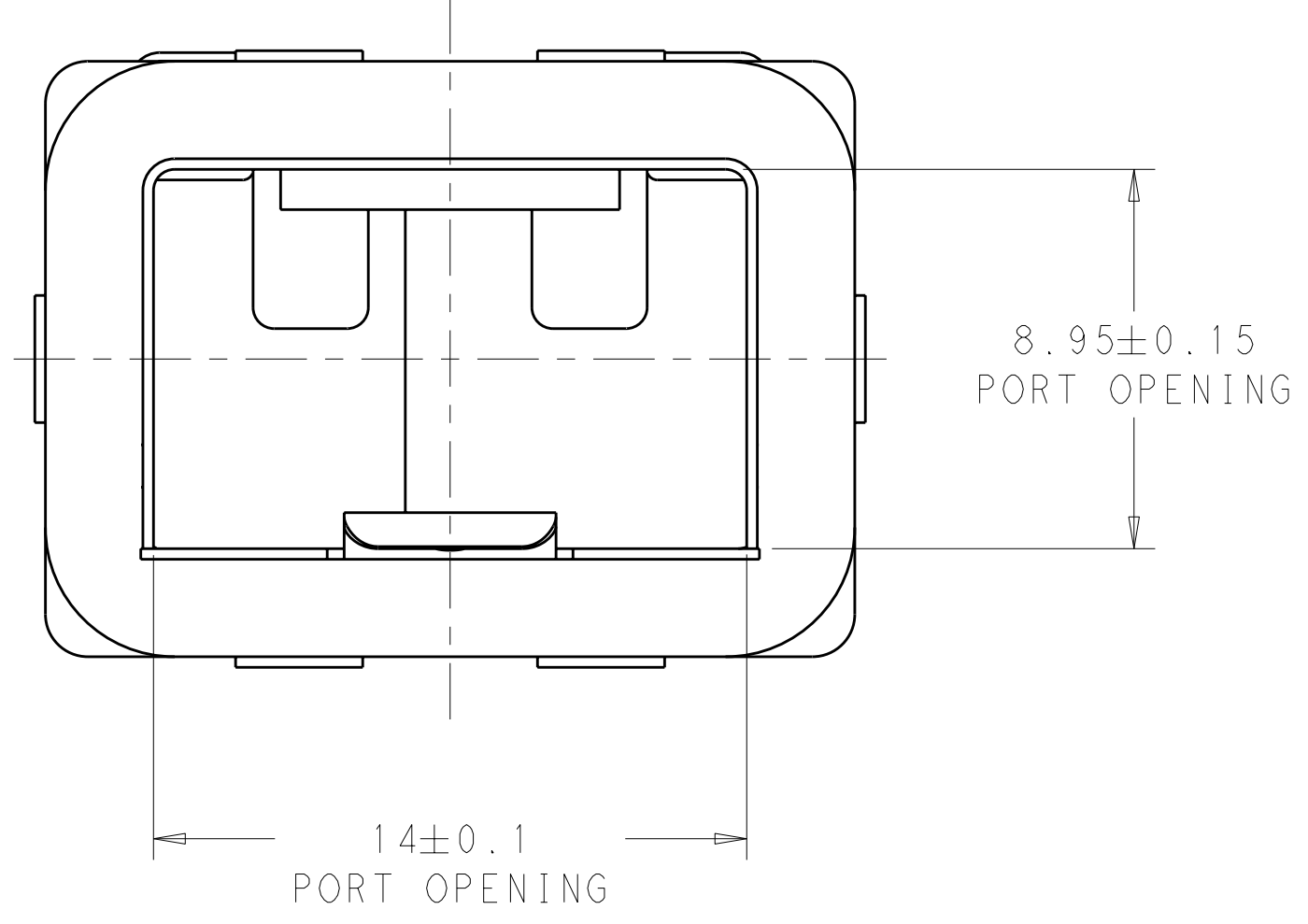
- 1 MATERIAL:
 CAGE ASSEMBLY: 0.25mm THICK NICKEL SILVER ALLOY
 GASKET RETENTION PLATE: STAINLESS STEEL
 EMI GASKET: PLATED FILLED SILICONE
 HEATSINK: ALUMINUM
 HEATSINK CLIP: STAINLESS STEEL
- 2 FINISH:
 HEATSINK: ELECTROLESS NICKEL FOR 2057085-1 THRU -3
 HEATSINK: HARD COAT ANODIZED FOR 2057085-4
 HEATSINK CLIP: PASSIVATE
3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 4 PADS AND VIAS CHASSIS GROUND.
- 5 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 6 MINIMUM PC BOARD THICKNESS:
 SINGLE SIDED = 1.45
- 7 REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 8 REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 9 DIMENSIONS APPLIES PRIOR TO INSERTION OF SFP MODULE.
- 10 HEATSINK CLIP AND HEATSINK SHIPPED UNASSEMBLED TO CAGE ASSEMBLY, CAGE ASSEMBLY TO BE PRESSED INTO THE PCB PRIOR TO ATTACHING THE HEATSINK CLIP AND HEATSINK TO THE CAGE ASSEMBLY.
- 11 HEATSINK REFERENCE PART NUMBERS:
 1829903-2 = 4.2mm HIGH - PCI.
 1829904-2 = 6.5mm HIGH - SAN
 1829905-2 = 13.5mm HIGH - NETWORKING, ELECTROLESS NICKEL
 1829905-4 = 13.5mm HIGH - NETWORKING, HARD COAT ANODIZED
 1963832-2 = 3.2mm HIGH - BLADE



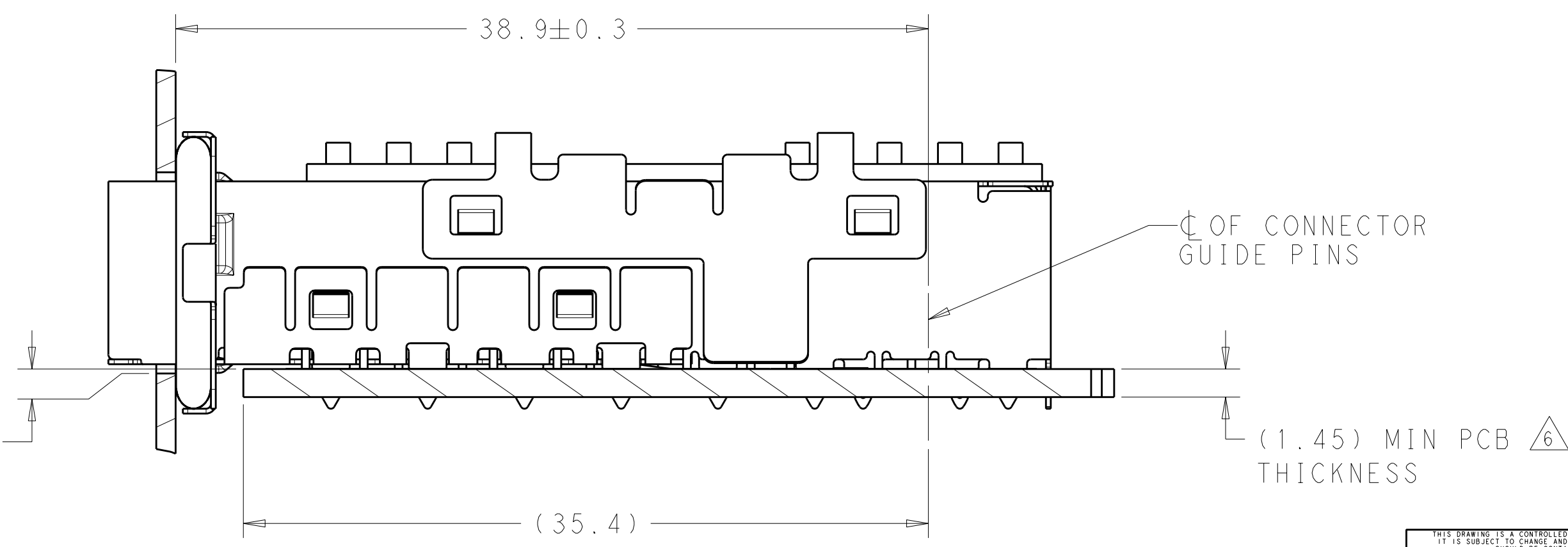
2057085-2 THRU -5
 RIGHT SIDE VIEW



2057085-1
 RIGHT SIDE VIEW



RECOMMENDED BEZEL CUT-OUT
 SCALE 3:1



2057085-1
 MOUNTED ON PCB
 SHOWN THRU RECOMMENDED BEZEL
 SCALE 4:1

APPLICATION	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
PCI	13.5		2057085-5	
NETWORKING, HARD COAT ANODIZED	22.8		2057085-4	
NETWORKING, ELECTROLESS NICKEL	22.8		2057085-3	
SAN	15.8		2057085-2	
BLADE	12.5		2057085-1	
APPLICATION	X		PART NUMBER	

DIMENSIONS: mm 		TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.05 ANGLES ±0.05		DWN Z.M. BEAM 22APR2008 CHK M.R. SCHMITT 22APR2008 APVD R.H. WERTZ 22APR2008		Tyco Electronics Harrisburg, PA 17105-3608	
MATERIAL:		FINISH:		NAME: SFP+ ENHANCED CAGE ASSEMBLY PRESS FIT, EMI GASKET, W/ HEAT SINK		SIZE: 114-13120 WEIGHT: A100779C=2057085	
CUSTOMER DRAWING				SCALE: 6:1		SHEET 1 OF 2 REV A	

